SLLS538B – JUNE 2002 – REVISED OCTOBER 2004

 Operate With 3-V to 5.5-V V_{CC} Supply Operate Up To 1 Mbit/s 	DB, DW, OR F (TOP	PW PACKAGE VIEW)
• Low Standby Current 1 μA Typ		20 FORCEOFF
• External Capacitors 4 \times 0.1 μ F	C1+[]2	19 V _{CC}
 Accept 5-V Logic Input With 3.3-V Supply 	V+[]3	18 GND
Latch-Up Performance Exceeds 100 mA Per	C1-[] 4	17 DOUT1
JESD 78, Class II	C2+[]5	16 RIN1
 RS-232 Bus-Pin ESD Protection Exceeds 	C2-[]6	15 ROUT1
	V-[] 7	14 🛛 FORCEON
±15 kV Using Human-Body Model (HBM)	DOUT2 🛛 8	13 DIN1
Applications	RIN2	12 DIN2
 Battery-Powered Systems, PDAs, 		11 INVALID
Notebooks, Laptops, Palmtop PCs, and	······································	

description/ordering information

Hand-Held Equipment

The SN65C3223 and SN75C3223 consist of two line drivers, two line receivers, and a dual charge-pump circuit with \pm 15-kV ESD protection pin to pin (serial-port connection pins, including GND). The devices provide the electrical interface between an asynchronous communication controller and the serial-port connector. The charge pump and four small external capacitors allow operation from a single 3-V to 5.5-V supply. The devices operate at data signaling rates up to 1 Mbit/s and a driver output slew rate of 24 V/µs to 150 V/µs

Flexible control options for power management are available when the serial port is inactive. The auto-powerdown feature functions when FORCEON is low and FORCEOFF is high. During this mode of operation, if the device does not sense a valid RS-232 signal, the driver outputs are disabled. If FORCEOFF is set low and EN is high, both drivers and receivers are shut off, and the supply current is reduced to 1 μ A. Disconnecting the serial port or turning off the peripheral drivers causes auto-powerdown to occur. Auto-powerdown can be disabled when FORCEON and FORCEOFF are high. With auto-powerdown enabled, the device is activated automatically when a valid signal is applied to any receiver input. The INVALID output is used to notify the user if an RS-232 signal is present at any receiver input. INVALID is high (valid data) if any receiver input voltage is greater than 2.7 V or less than –2.7 V or has been between –0.3 V and 0.3 V for less than 30 μ s. Refer to Figure 4 for receiver input levels.

TA	PACKA	GE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
		Tube of 25	SN75C3223DW	7500000
	SOIC – DW	Reel of 2000	SN75C3223DWR	75C3223
0°C to 70°C	SSOP – DB	Reel of 2000	SN75C3223DBR	CA3223
		Tube of 70	SN75C3223PW	
	TSSOP – PW	Reel of 2000	SN75C3223PWR	CA3223
	0010 014	Tube of 25	SN65C3223DW	
	SOIC – DW	Reel of 2000	SN65C3223DWR	65C3223
–40°C to 85°C	SSOP – DB	Reel of 2000	SN65C3223DBR	CB3223
	7000D DW	Tube of 70	SN65C3223PW	0.00000
	TSSOP – PW	Reel of 2000	SN65C3223PWR	CB3223

ORDERING INFORMATION

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



Copyright © 2004, Texas Instruments Incorporated

SLLS538B - JUNE 2002 - REVISED OCTOBER 2004

Function Tables

			EACH DRIVER		
		INPUTS		OUTPUT	
DIN	FORCEON	FORCEOFF	VALID RIN RS-232 LEVEL	DOUT	DRIVER STATUS
Х	Х	L	Х	Z	Powered off
L	Н	Н	Х	Н	Normal operation with
Н	Н	Н	Х	L	auto-powerdown disabled
L	L	Н	Yes	Н	Normal operation with
н	L	Н	Yes	L	auto-powerdown enabled
L	L	Н	No	Z	Powered off by
Н	L	Н	No	Z	auto-powerdown feature

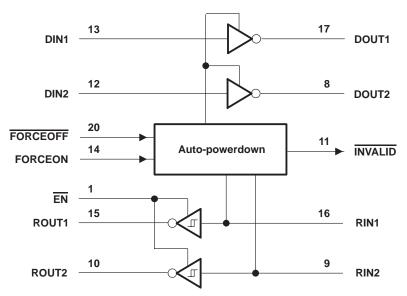
H = high level, L = low level, X = irrelevant, Z = high impedance

EACH RECEIVER

	INP	PUTS	OUTPUT
RIN	EN	VALID RIN RS-232 LEVEL	ROUT
L	L	Х	Н
н	L	Х	L
Х	Н	Х	Z
Open	L	No	Н

H = high level, L = low level, X = irrelevant, Z = high impedance (off), Open = input disconnected or connected driver off

logic diagram (positive logic)





SLLS538B – JUNE 2002 – REVISED OCTOBER 2004

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V _{CC} (see Note 1) Positive output supply voltage range, V+ (see Note 1) Negative output supply voltage range, V– (see Note 1)	0.3 V to 7 V 0.3 V to -7 V
Supply voltage difference, V+ – V– (see Note 1)	
Input voltage range, VI: Driver, FORCEOFF, FORCEON, EN	$\dots \dots \dots \dots -0.3 \text{ V to 6 V}$
Receiver	–25 V to 25 V
Output voltage range, V _O : Driver	13.2 V to 13.2 V
Receiver, INVALID	\dots –0.3 V to V _{CC} + 0.3 V
Package thermal impedance, θ_{JA} (see Notes 2 and 3): DB package	
	58°C/W
	83°C/W
Operating virtual junction temperature, T _J	
Storage temperature range, T _{stg}	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltages are with respect to network GND.

- 2. Maximum power dissipation is a function of $T_J(max)$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
- 3. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 4 and Figure 6)

				MIN	NOM	MAX	UNIT
	cc Supply voltage		$V_{CC} = 3.3 V$	3	3.3	3.6	
Vcc			$V_{CC} = 5 V$	4.5	5	5.5	V
		r and control high-level input voltage $DIN, \overline{EN}, \overline{FORCEOFF}, \overline{VCC} = 3.3 V$ FORCEON $V_{CC} = 5 V$	$V_{CC} = 3.3 V$	2			V
VIH	Driver and control high-level input voltage		$V_{CC} = 5 V$	2.4			V
VIL	Driver and control low-level input voltage	DIN, EN, FORCEOFF, FORCEO	NC			0.8	V
	Driver and control input voltage	DIN, EN, FORCEOFF, FORCEO	NC	0		5.5	N/
VI	Receiver input voltage			-25		25	V
т.			SN65C3223	-40		85	°C
Τ _Α	Operating free-air temperature		SN65C3223	0		70	U

NOTE 4: Test conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V ± 0.3 V; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at V_{CC} = 5 V ± 0.5 V.

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 6)

PARAMETER		TEST CONDITIONS	MIN	TYP‡	MAX	UNIT	
Ц	Input leakage current	EN, FORCEOFF, FORCEON			±0.01	±1	μΑ
		Auto-powerdown disabled	$\frac{\text{No load,}}{\text{FORCEOFF, FORCEON at V}_{\text{CC}}}$		0.3	1	mA
ICC	Supply current	Powered off	No load, FORCEOFF at GND		1	10	
		Auto-powerdown enabled	No load, FORCEOFF at V _{CC} , FORCEON at GND, All RIN are open or grounded		1	10	μΑ

[‡] All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.

NOTE 4: Test conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V ± 0.3 V; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at V_{CC} = 5 V ± 0.5 V.



SLLS538B - JUNE 2002 - REVISED OCTOBER 2004

DRIVER SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 6)

	PARAMETER	TE	ST CONDITION	S	MIN	TYP†	MAX	UNIT
VOH	High-level output voltage	DOUT at $R_L = 3 k\Omega$ to G	ND		5	5.4		V
VOL	Low-level output voltage	DOUT at $R_L = 3 k\Omega$ to G	DOUT at $R_L = 3 k\Omega$ to GND			-5.4		V
Iн	High-level input current	VI = VCC				±0.01	±1	μΑ
۱ _{IL}	Low-level input current	V _I at GND				±0.01	±1	μΑ
		V _{CC} = 3.6 V,	VO = 0 V			±35	±60	
los	Short-circuit output current‡	V _{CC} = 5.5 V,	VO = 0 V			±35	±90	mA
r _o	Output resistance	V_{CC} , V+, and V- = 0 V,	$V_{O} = \pm 2 V$		300	10M		Ω
		FORCEOFF = GND	$V_{O} = \pm 12 V$,	V_{CC} = 3 V to 3.6 V			±25	
loff	Output leakage current	FORGEOFF = GND	$V_{O} = \pm 10 V$,	V_{CC} = 4.5 V to 5.5 V			±25	μΑ

[†] All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.

[‡] Short-circuit durations should be controlled to prevent exceeding the device absolute power-dissipation ratings, and not more than one output should be shorted at a time.

NOTE 4: Test conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V ± 0.3 V; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at V_{CC} = 5 V ± 0.5 V.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 6)

	PARAMETER		TEST CONDITIONS		MIN	TYP†	MAX	UNIT
	Maximum data rate $R_L = 3 k\Omega$, (see Figure 1) One DOUT switching	C _L = 1000 pF		250				
		C _L = 250 pF,	V_{CC} = 3 V to 4.5 V	1000			kbit/s	
		one beer entering	C _L = 1000 pF,	V_{CC} = 4.5 V to 5.5 V	1000			
tsk(p)	Pulse skew [§]	$C_{L} = 150 \text{ pF} \text{ to } 2500 \text{ pF},$	$R_L = 3 \ k\Omega$ to 7 $k\Omega$,	See Figure 2		300		ns
SR(tr)	Slew rate, transition region (see Figure 1)	V _{CC} = 3.3 V, R _L = 3 kΩ to 7 kΩ	C _L = 150 pF to 1000	pF	18		150	V/µs

[†] All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.

\$ Pulse skew is defined as $|tp_{LH} - tp_{HL}|$ of each channel of the same device. NOTE 4: Test conditions are C1-C4 = 0.1 μ F at V_{CC} = 3.3 V ± 0.3 V; C1 = 0.047 μ F, C2-C4 = 0.33 μ F at V_{CC} = 5 V ± 0.5 V.



SLLS538B - JUNE 2002 - REVISED OCTOBER 2004

RECEIVER SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 6)

	PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
VOH	High-level output voltage	$I_{OH} = -1 \text{ mA}$	V _{CC} – 0.6	V _{CC} – 0.1		V
VOL	Low-level output voltage	I _{OL} = 1.6 mA			0.4	V
N/	Desitive spin picture three held welters	V _{CC} = 3.3 V		1.6	2.4	
VIT+	Positive-going input threshold voltage	$V_{CC} = 5 V$		1.9	2.4	V
	No. 2010 and the stand thread add and the set	V _{CC} = 3.3 V	0.6	1.1		
VIT-	Negative-going input threshold voltage	$V_{CC} = 5 V$	0.8	1.4		V
V _{hys}	Input hysteresis (V _{IT+} – V _{IT} –)			0.5		V
loff	Output leakage current	$\overline{EN} = V_{CC}$		±0.05	±10	μΑ
r _i	Input resistance	$V_I = \pm 3 V \text{ to } \pm 25 V$	3	5	7	kΩ

[†] All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.

NOTE 4: Test conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V ± 0.3 V; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at V_{CC} = 5 V ± 0.5 V.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4)

PARAMETER		TEST (TEST CONDITIONS		MAX	UNIT
^t PLH	Propagation delay time, low- to high-level output	CL= 150 pF,	See Figure 3	150		ns
^t PHL	Propagation delay time, high- to low-level output	C _L = 150 pF,	See Figure 3	150		ns
t _{en}	Output enable time	C _L = 150 pF, See Figure 4	$R_L = 3 k\Omega$,	200		ns
^t dis	Output disable time	C _L = 150 pF, See Figure 4	RL = 3 kΩ,	200		ns
^t sk(p)	Pulse skew [‡]	See Figure 3		50		ns

[†] All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.

[‡]Pulse skew is defined as |t_{PLH} – t_{PHL}| of each channel of the same device.

NOTE 4: Test conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V ± 0.3 V; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at V_{CC} = 5 V ± 0.5 V.



SLLS538B - JUNE 2002 - REVISED OCTOBER 2004

AUTO-POWERDOWN SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 5)

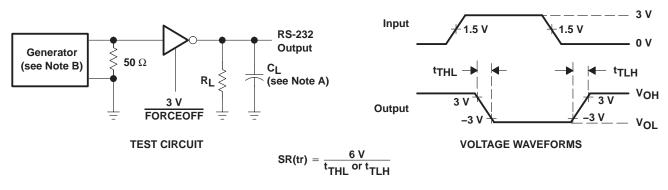
	PARAMETER	TEST C	ONDITIONS	MIN	MAX	UNIT
V _{T+(valid)}	Receiver input threshold for INVALID high-level output voltage	FORCEON = GND,	$\overline{FORCEOFF} = V_{CC}$		2.7	V
V _{T-(valid)}	Receiver input threshold for INVALID high-level output voltage	FORCEON = GND,	$\overline{FORCEOFF} = V_{CC}$	-2.7		V
V _{T(invalid)}	Receiver input threshold for INVALID low-level output voltage	FORCEON = GND,	$\overline{FORCEOFF} = V_{CC}$	-0.3	0.3	V
VOH	INVALID high-level output voltage	$\frac{I_{OH} = -1 \text{ mA}}{FORCEOFF} = V_{CC}$	FORCEON = GND,	V _{CC} – 0.6		V
VOL	INVALID low-level output voltage	$\frac{I_{OL} = 1.6 \text{ mA}}{FORCEOFF} = V_{CC}$	FORCEON = GND,		0.4	V

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 5)

	PARAMETER	TYP†	UNIT
^t valid	Propagation delay time, low- to high-level output	1	μs
^t invalid	Propagation delay time, high- to low-level output	30	μs
t _{en}	Supply enable time	100	μs

[†] All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

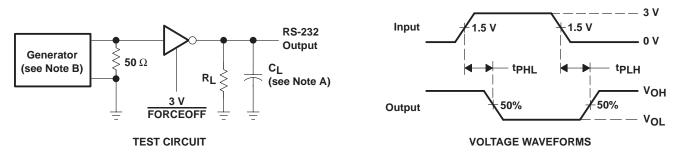
B. The pulse generator has the following characteristics: PRR = 250 kbit/s, $Z_0 = 50 \Omega$, 50% duty cycle, $t_f \le 10$ ns. $t_f \le 10$ ns.

Figure 1. Driver Slew Rate



SLLS538B – JUNE 2002 – REVISED OCTOBER 2004

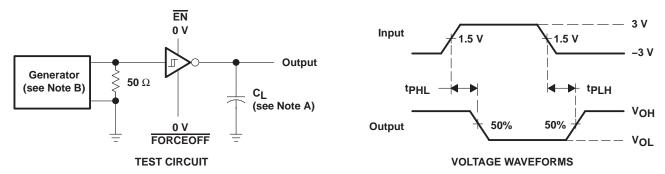
PARAMETER MEASUREMENT INFORMATION



NOTES: A. CL includes probe and jig capacitance.

B. The pulse generator has the following characteristics: PRR = 250 kbit/s, $Z_O = 50 \Omega$, 50% duty cycle, $t_r \le 10$ ns, $t_f \le 10$ ns.

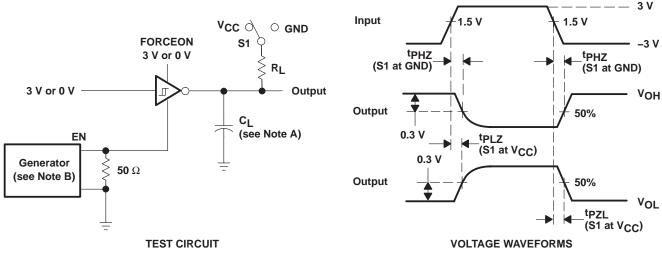
Figure 2. Driver Pulse Skew



NOTES: A. C_L includes probe and jig capacitance.

B. The pulse generator has the following characteristics: $Z_O = 50 \Omega$, 50% duty cycle, $t_f \le 10 \text{ ns}$. $t_f \le 10 \text{ ns}$.

Figure 3. Receiver Propagation Delay Times



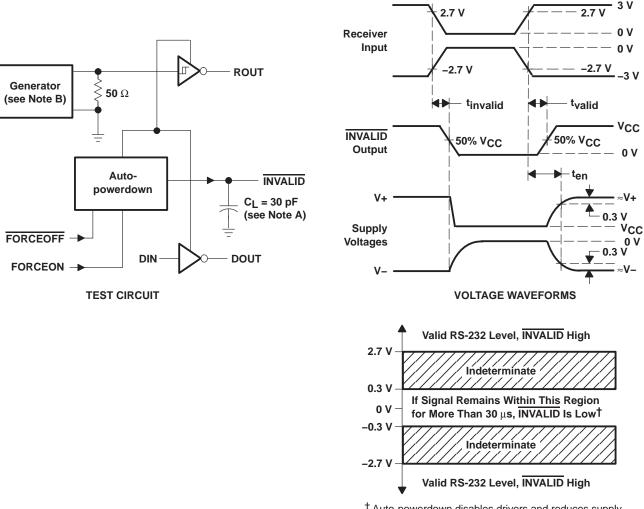
NOTES: A. CL includes probe and jig capacitance.

B. The pulse generator has the following characteristics: $Z_{O} = 50 \Omega$, 50% duty cycle, $t_{f} \le 10$ ns. $t_{f} \le 10$ ns.

Figure 4. Receiver Enable and Disable Times



SLLS538B - JUNE 2002 - REVISED OCTOBER 2004



PARAMETER MEASUREMENT INFORMATION

 † Auto-powerdown disables drivers and reduces supply current to 1 $\mu A.$

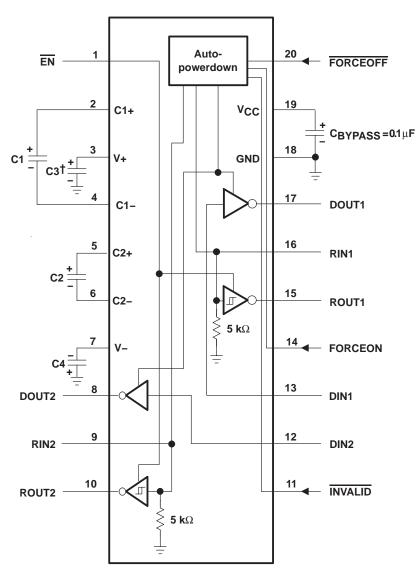
NOTES: A. CL includes probe and jig capacitance.

B. The pulse generator has the following characteristics: PRR = 5 kbit/s, $Z_0 = 50 \Omega$, 50% duty cycle, $t_f \le 10$ ns. $t_f \le 10$ ns.

Figure 5. INVALID Propagation Delay Times and Supply Enabling Time



SLLS538B - JUNE 2002 - REVISED OCTOBER 2004



APPLICATION INFORMATION

 † C3 can be connected to V_CC or GND. NOTE A: Resistor values shown are nominal.

V _{CC} vs CAPACITOR VALUES					
Vcc	C1	C2, C3, C4			
3.3 V ± 0.3 V 5 V ± 0.5 V	0.1 μF 0.047 μF	0.1 μF 0.33 μF			
3 V to 5.5 V	0.1 μ F	0.47 μF			

Figure 6. Typical Operating Circuit and Capacitor Values



PACKAGING INFORMATION

www ti com

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finisl	n MSL Peak Temp ⁽³⁾
SN65C3223DBR	ACTIVE	SSOP	DB	20	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR Level-1-235C-UNLIM
SN65C3223DW	ACTIVE	SOIC	DW	20	25	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR Level-1-235C-UNLIM
SN65C3223DWR	ACTIVE	SOIC	DW	20	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR Level-1-235C-UNLIM
SN65C3223PW	ACTIVE	TSSOP	PW	20	70	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN65C3223PWR	ACTIVE	TSSOP	PW	20	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN75C3223DBR	ACTIVE	SSOP	DB	20	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR Level-1-235C-UNLIM
SN75C3223DW	ACTIVE	SOIC	DW	20	25	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR Level-1-235C-UNLIM
SN75C3223DWR	ACTIVE	SOIC	DW	20	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR Level-1-235C-UNLIM
SN75C3223PW	ACTIVE	TSSOP	PW	20	70	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN75C3223PWR	ACTIVE	TSSOP	PW	20	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details. TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer:The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

DW (R-PDSO-G20)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-013 variation AC.



MECHANICAL DATA

MSSO002E - JANUARY 1995 - REVISED DECEMBER 2001

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-150



MECHANICAL DATA

MTSS001C - JANUARY 1995 - REVISED FEBRUARY 1999

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-153



IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products		Applications	
Amplifiers	amplifier.ti.com	Audio	www.ti.com/audio
Data Converters	dataconverter.ti.com	Automotive	www.ti.com/automotive
DSP	dsp.ti.com	Broadband	www.ti.com/broadband
Interface	interface.ti.com	Digital Control	www.ti.com/digitalcontrol
Logic	logic.ti.com	Military	www.ti.com/military
Power Mgmt	power.ti.com	Optical Networking	www.ti.com/opticalnetwork
Microcontrollers	microcontroller.ti.com	Security	www.ti.com/security
		Telephony	www.ti.com/telephony
		Video & Imaging	www.ti.com/video
		Wireless	www.ti.com/wireless

Mailing Address:

Texas Instruments

Post Office Box 655303 Dallas, Texas 75265

Copyright © 2005, Texas Instruments Incorporated